

LTC1401

Complete SO-8, 12-Bit, 200ksps ADC with Shutdown

The LTC[®]1401 is a complete 200ksps, 12-bit A/D con-

verter that converts 0V to 2.048V unipolar input and draws

only 15mW from a single 3V supply. This easy-to-use

device comes complete with a 315ns sample-and-hold

and a precision reference. Maximum DC specifications

include ±1LSB INL, ±1LSB DNL and 45ppm/°C full-scale

The LTC1401 has three power saving modes: Nap and

Sleep, through the serial interface and Shutdown by

setting the SHDN pin to zero. In Nap mode, it consumes

only 1.5mW of power and can wake up and convert

immediately. In Sleep (Shutdown) mode, it consumes

19.5µW (13.5µW) of power typically. Upon power-up

from Sleep or Shutdown mode, a reference ready (REFRDY) signal is available in the serial word to indicate that the

The 3-wire serial port allows compact and efficient data

transfer to a wide range of microprocessors, microcon-

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MICROWIRE is a trademark of National Semiconductor Corporation.

reference has settled and the chip is ready to convert.

DESCRIPTION

drift over temperature.

trollers and DSPs.

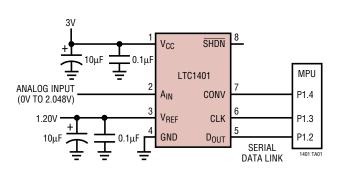
FEATURES

- Complete 12-Bit ADC with Reference in SO-8
- Single Supply 3V Operation
- Sample Rate: 200ksps
- Power Dissipation: 15mW (Typ)
- 68dB S/(N + D) and 72dB THD at 50kHz
- No Missing Codes Over Temperature
- Nap Mode with Instant Wake-Up: 1.5mW
- Sleep Mode: 19.5µW
- Shutdown Mode: 13.5µW
- High Impedance Analog Input
- Input Range (0.5mV/LSB): 0V to 2.048V
- Internal Reference Can Be Overdriven Externally
- 3-Wire Interface to DSPs and Processors (SPI and MICROWIRE[™] Compatible)

APPLICATIONS

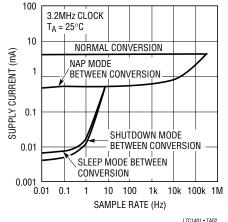
- Low Power and Battery-Operated Systems
- Handheld or Portable Instruments
- High Speed Data Acquisition
- Digital Signal Processing
- Multiplexed Data Acquisition Systems
- Telecommunication
- Digital Radio
- Spectrum Analysis

TYPICAL APPLICATION



Single 3V Supply, 200kHz, 12-Bit Sampling A/D Converter

Power Consumption vs Sample Rate



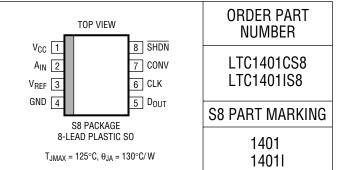


ABSOLUTE MAXIMUM RATINGS

(Notes 1, 2)

Supply Voltage (V _{CC})
Analog Input Voltage (Note 3) $\dots -0.3V$ to (V _{CC} + 0.3V)
Digital Input Voltage (Note 4)–0.3V to 12V
Digital Output Voltage $-0.3V$ to (V _{CC} + 0.3V)
Power Dissipation 300mW
Operating Ambient Temperature Range
LTC1401C0°C to 70°C
LTC14011 – 40°C to 85°C
Operating Junction Temperature 125°C
Storage Temperature Range –65°C to 150°C
Lead Temperature (Soldering, 10 sec)

PACKAGE/ORDER INFORMATION



Consult factory for PDIP packages and Military grade parts.

POWER REQUIREMENTS (Note 5)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V _{CC}	Supply Voltage			2.7	3.0	3.6	V
Icc	Supply Current	f _{SAMPLE} = 200ksps	•		5	10	mA
		Nap Mode			0.5	1.0	mA
		Sleep Mode			6.5	15	μA
		Shutdown Mode			4.5	10	μA
PD	Power Dissipation	f _{SAMPLE} = 200ksps	•		15	30	mW
		Nap Mode			1.5	3.0	mW
		Sleep Mode			19.5	45	μW
		Shutdown Mode			13.5	30	μW

ANALOG INPUT (Note 5)

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
V _{IN}	Analog Input Range		•		0 to 2.048		V
IIN	Analog Input Leakage Current	During Conversions (Hold Mode)	•			±1	μA
C _{IN}	Analog Input Capacitance	Between Conversions (Sample Mode) During Conversions (Hold Mode)			45 5		pF pF

INTERNAL REFERENCE CHARACTERISTICS (Note 5)

PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
V _{REF} Output Voltage	I _{OUT} = 0		1.180	1.200	1.220	V
V _{REF} Output Tempco	I _{OUT} = 0	•		±10	±45	ppm/°C
V _{REF} Line Regulation	$2.7V \le V_{CC} \le 3.6V$			0.01		LSB/V
V _{REF} Load Regulation	$0 \le I_{OUT} \le 1mA$			2		LSB/mA
V _{REF} Wake-Up Time from Sleep or Shutdown Mode	C _{VREF} = 10µF			3		ms



CONVERTER CHARACTERISTICS With internal reference (Note 5)

PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
Resolution (No Missing Codes)		•	12			Bits
Integral Linearity Error	(Note 7)	•			±1	LSB
Differential Linearity Error		•			±1	LSB
Offset Error					±6	LSB
		•			±8	LSB
Full-Scale Error					±15	LSB
Full-Scale Tempco	$I_{OUT(REF)} = 0$	•		±10	±45	ppm/°C

DYNAMIC ACCURACY (Note 5)

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
S/(N + D)	Signal-to-Noise Plus Distortion Ratio	50kHz Input Signal 100kHz Input Signal	•	65	68 65		dB dB
THD	Total Harmonic Distortion Up to 5th Harmonic	50kHz Input Signal 100kHz Input Signal	•		-72 -66	-65	dB dB
	Peak Harmonic or Spurious Noise	50kHz Input Signal 100kHz Input Signal	•		-74 -67	-65	dB dB
IMD	Intermodulation Distortion	f _{IN1} = 49.853kHz, f _{IN2} = 53.076kHz			-69		dB
	Full Power Bandwidth				2		MHz
	Full Linear Bandwidth (S/(N + D) \ge 68dB)				50		kHz

DIGITAL INPUTS AND OUTPUTS (Note 5)

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
V _{IH}	High Level Input Voltage	V _{CC} = 3.6V	•	2.0			V
V _{IL}	Low Level Input Voltage	V _{CC} = 2.7V	•			0.8	V
I _{IN}	Digital Input Current	$V_{IN} = 0V$ to V_{CC}	•			±10	μA
CIN	Digital Input Capacitance				5		pF
V _{OH}	High Level Output Voltage	$V_{CC} = 2.7V, I_0 = -10\mu A$ $V_{CC} = 2.7V, I_0 = -200\mu A$	•	2.40 2.25	2.64 2.50		V V
V _{OL}	Low Level Output Voltage	V _{CC} = 2.7V, I ₀ = 400µA	•		0.13	0.4	V
I _{OZ}	Hi-Z Output Leakage D _{OUT}	$V_{OUT} = 0V \text{ to } V_{CC}$	•			±10	μA
C _{OZ}	Hi-Z Output Capacitance D _{OUT}				15		pF
ISOURCE	Output Source Current	V _{OUT} = 0			-5		mA
I _{SINK}	Output Sink Current	$V_{OUT} = V_{CC}$			10		mA



TIMING CHARACTERISTICS (Note 5)

SYMBOL	PARAMETER	CONDITIONS		MIN	ТҮР	MAX	UNITS
f _{SAMPLE(MAX)}	Maximum Sampling Frequency			200			kHz
t _{CONV}	Conversion Time	f _{CLK} = 3.2MHz	•			4.1	μs
t _{ACQ}	Acquisition Time				315		ns
f _{CLK}	CLK Frequency		•	0.1		3.2	MHz
t _{CLK}	CLK Pulse Width	(Note 6)	•	60			ns
t _{WK(NAP)}	Time to Wake Up from Nap Mode				350		ns
t ₁	CLK Pulse Width to Return to Active Mode		•	60			ns
t ₂	CONV↑ to CLK↑ Setup Time		•	100			ns
t ₃	CONV↑ After Leading CLK↑		•	0			ns
t ₄	CONV Pulse Width	(Note 8)	•	50			ns
t ₅	Time from CLK↑ to Sample Mode				80		ns
t ₆	Aperture Delay of Sample-and-Hold	Jitter < 50ps			45		ns
t ₇	Minimum Delay Between Conversion	(Note 6)	•		350	550	ns
t ₈	Delay Time, CLK↑ to D _{OUT} Valid	C _{LOAD} = 20pF			60	120	ns
tg	Delay Time, CLK↑ to D _{OUT} Hi-Z	C _{LOAD} = 20pF	•		60	120	ns
t ₁₀	Time from Previous Data Remains Valid After CLK [↑]	C _{LOAD} = 20pF	•	15	50		ns

The \bullet denotes specifications which apply over the full operating temperature range; all other limits and typicals apply to T_A = 25°C.

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: All voltage values are with respect to GND.

Note 3: When these pin voltages are taken below GND or above V_{CC} , they will be clamped by internal diodes. This product can handle input currents greater than 40mA without latch-up if the pin is driven below GND or above V_{CC} .

Note 4: When these pin voltages are taken below GND, they will be clamped by internal diodes. This product can handle input currents greater than 40mA without latch-up if the pin is driven below GND. These pins are not clamped to V_{CC} .

Note 5: $V_{CC} = 3V$, $f_{SAMPLE} = 200$ kHz, $t_r = t_f = 5$ ns unless otherwise specified.

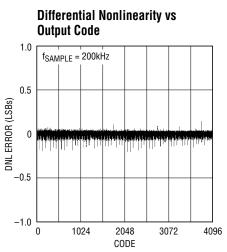
Note 6: Guaranteed by design, not subject to test.

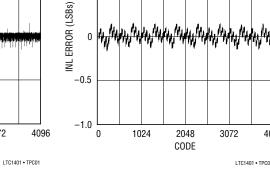
Note 7: Integral nonlinearity is defined as the deviation of a code from a straight line passing through the actual endpoints of the transfer curve. The deviation is measured from the center of the quantization band.

Note 8: The rising edge of CONV starts a conversion. If CONV returns low at a bit decision point during the conversion, it can create small errors. For best performance, ensure that CONV returns low either within 120ns after the conversion starts (i.e., before the first bit decision) or after the 14 clock cycles. (Figure 13 Timing Diagram).



TYPICAL PERFORMANCE CHARACTERISTICS





 $T_A = 25^{\circ}C$

f_{SAMPLE} = 200kHz

Integral Nonlinearity vs

Output Code

f_{SAMPLE} = 200kHz

1.0

0.5

0

-10

-20

-30

-40

-50

-60

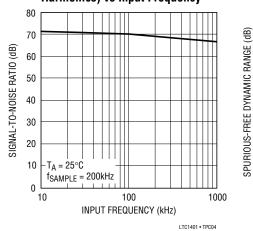
-70

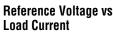
-80

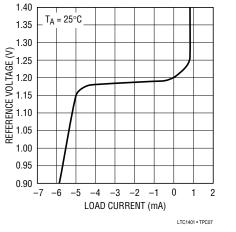
-90

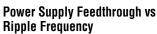
10

Peak Harmonic or Spurious Noise Signal-to-Noise Ratio (Without Harmonics) vs Input Frequency vs Input Frequency



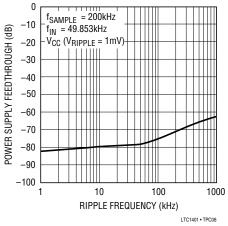




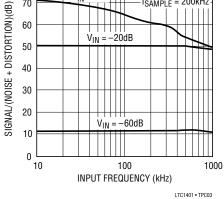


100

INPUT FREQUENCY (kHz)



S/(N + D) vs Input Frequency and Amplitude 80 $T_A = 25^{\circ}C$ $V_{IN} = 0dB$ f_{SAMPLE} = 200kHz 70 60 $V_{IN} = -20$ dB 50 40



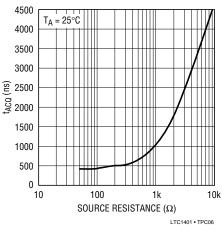
Acquisition Time vs **Source Impedance**

4096

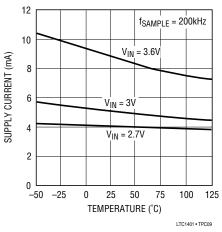
1000

LTC1401 • TPC05

LTC1401 • TPC02



Supply Current vs Temperature





PIN FUNCTIONS

 V_{CC} (Pin 1): Positive Supply, 3V. Bypass to GND (10 μ F tantalum in parallel with 0.1 μ F ceramic).

AIN (Pin 2): Analog Input. OV to 2.048V.

 V_{REF} (Pin 3): 1.2V Reference Output. Bypass to GND (10µF tantalum in parallel with 0.1µF ceramic).

GND (Pin 4): Ground. GND should be tied directly to an analog ground plane.

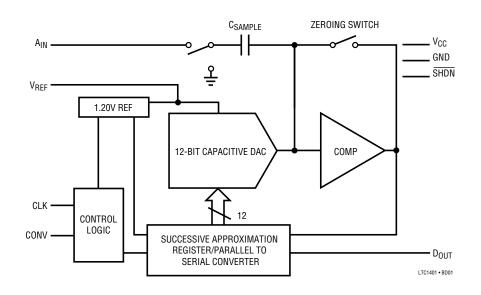
D_{OUT} (**Pin 5**): The A/D conversion result is shifted out from this pin.

CLK (Pin 6): Clock. This clock synchronizes the serial data transfer. A minimum CLK pulse of 60ns signals the ADC to wake up from Nap or Sleep mode.

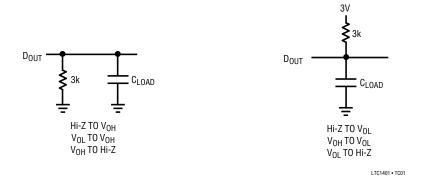
CONV (Pin 7): Conversion Start Signal. This active high signal starts a conversion on its rising edge. Keeping CLK low and pulsing CONV two/four times will put the ADC into Nap/Sleep mode.

SHDN (Pin 8): Shutdown Input. Pull this pin Low to put the ADC in Shutdown mode and save power (REFRDY will go Low). The device will draw 4.5µA in this mode.

FUNCTIONAL BLOCK DIAGRAM



TEST CIRCUITS





Conversion Details

The LTC1401 uses a successive approximation algorithm and an internal sample-and-hold circuit to convert an analog signal to a 12-bit serial output based on a precision internal reference. The control logic provides an easy interface to microprocessors and DSPs through serial 3-wire connections.

A rising edge on the CONV input starts a conversion. At the start of a conversion the successive approximation register (SAR) is reset. Once a conversion cycle has begun, it cannot be restarted.

During conversion, the internal 12-bit capacitive DAC output is sequenced by the SAR from the most significant bit (MSB) to the least significant bit (LSB). Referring to Figure 1, the A_{IN} input connects to the sample-and-hold capacitor during the acquire phase and the comparator offset is nulled by the feedback switch. In this acquire phase, it typically takes 315ns for the sample-and-hold capacitor to acquire the analog signal. During the convert phase, the comparator feedback switch opens, putting the comparator into the compare mode. The input switches C_{SAMPLE} to ground, injecting the analog input charge onto the summing junction. This input charge is successively compared with the binary-weighted charges supplied by the capacitive DAC. Bit decisions are made by the high speed comparator. At the end of a conversion, the DAC

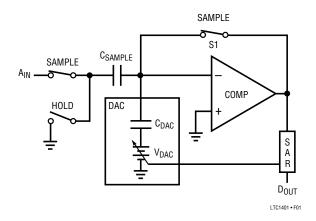


Figure 1. A_{IN} Input

output balances the A_{IN} input charge. The SAR contents (a 12-bit data word) which represent the input voltage, are presented through the serial pin D_{OUT} .

Dynamic Performance

The LTC1401 has excellent high speed sampling capability. FFT (Fast Fourier Transform) test techniques are used to test the ADC's frequency response, distortion and noise at the rated throughput. By applying a low distortion sine wave and analyzing the digital output using an FFT algorithm, the ADC's spectral content can be examined for frequencies outside the fundamental. Figure 2a shows a typical LTC1401 FFT plot.

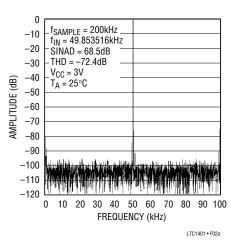


Figure 2a. LTC1401 Nonaveraged, 4096 Point FFT Plot with 50kHz Input Frequency

Signal-to-Noise Ratio

The signal-to-noise plus distortion ratio [S/(N+D)] is the ratio between the RMS amplitude of the fundamental input frequency to the RMS amplitude of all other frequency components at the A/D output. The output is band limited to frequencies from DC to half the sampling frequency. Figure 2a shows a typical spectral content with a 200kHz sampling rate and a 50kHz input. The dynamic performance is excellent for input frequencies up to the Nyquist limit of 100kHz as shown in Figure 2b.



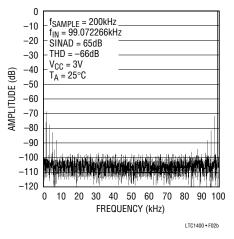


Figure 2b. LTC1401 Nonaveraged, 4096 Point FFT Plot with 100kHz Input Frequency

Effective Number of Bits

The effective number of bits (ENOBs) is a measurement of the effective resolution of an ADC and is directly related to the S/(N + D) by the equation:

$$N = \frac{S/(N+D) - 1.76}{6.02}$$

where N is the effective number of bits of resolution and S/(N + D) is expressed in dB. Figure 3 shows ENOBs vs Input Frequency.

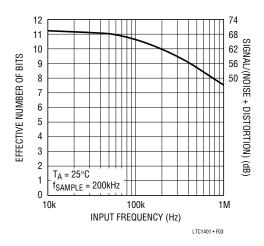


Figure 3. Effective Bits and Signal-to-Noise + Distortion vs Input Frequency

Total Harmonic Distortion

Total harmonic distortion (THD) is the ratio of the RMS sum of all harmonics of the input signal to the fundamental itself. The out-of-band harmonics alias into the frequency band between DC and half of the sampling frequency. THD is expressed as:

THD = 20log
$$\frac{\sqrt{V2^2 + V3^2 + ...Vn^2}}{V1}$$

Where V1 is the RMS amplitude of the fundamental frequency and V2 through Vn are the amplitudes of the second through nth harmonics. THD vs input frequency is shown in Figure 4. The LTC1401 has good distortion performance up to the Nyquist frequency and beyond.

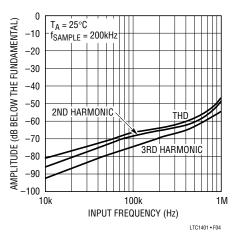


Figure 4. Distortion vs Input Frequency

Intermodulation Distortion

If the ADC input signal consists of more than one spectral component, the ADC transfer function nonlinearity can produce intermodulation distortion (IMD) in addition to THD. IMD is the change in one sinusoidal input caused by the presence of another sinusoidal input at a different frequency.

If two pure sine waves of frequencies fa and fb are applied to the ADC input, nonlinearities in the ADC transfer function can create distortion products at sum and differ-



ence frequencies of mfa \pm nfb, where m and n = 0, 1, 2, 3, etc. For example, the 2nd order IMD terms include (fa + fb) and (fa - fb) while 3rd order IMD terms includes (2fa + fb), (2fa - fb), (fa + 2fb) and (fa - 2fb). If the two input sine waves are equal in magnitude, the value (in decibels) of the 2nd order IMD products can be expressed by the following formula.

 $IMD(fa \pm fb) = 20log \frac{Amplitude at (fa \pm fb)}{Amplitude at fa}$

Figure 5 shows the IMD performance at a 50kHz input.

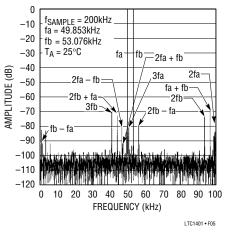


Figure 5. Intermodulation Distortion Plot

Peak Harmonic or Spurious Noise

The peak harmonic or spurious noise is the largest spectral component excluding the input signal and DC. This value is expressed in decibels relative to the RMS value of a full-scale input signal.

Full Power and Full Linear Bandwidth

The full power bandwidth is the input frequency at which the amplitude of the reconstructed fundamental is reduced by 3dB for a full-scale input signal.

The full linear bandwidth is the input frequency at which the S/(N+D) has dropped to 68dB (11 effective bits).

Driving the Analog Input

The analog input of the LTC1401 is easy to drive. It draws only one small current spike while charging the sampleand-hold capacitor at the end of a conversion. During conversion, the analog input draws only a small leakage current. The only requirement is that the amplifier driving the analog input must settle after the small current spike before the next conversion starts. Any op amp that settles in 315ns to small load current transients will allow maximum speed operation. If a slower op amp is used, more settling time can be provided by increasing the time between conversions. Suitable devices capable of driving the ADC's A_{IN} input include the LT[®]1498 and the LT1630 op amps.

The following list is a summary of the op amps that are suitable for driving the LTC1401, more detailed information is available in the Linear Technology databooks and the LinearView[™] CD-ROM.

LT1215/LT1216: Dual and quad 23MHz, 50V/ μ s single supply op amps. Single 5V to \pm 15V supplies, 6.6mA specifications, 90ns settling to 0.5LSB.

LT1229/LT1230: Dual and quad 100MHz current feedback amplifiers. $\pm 2V$ to $\pm 15V$ supplies, 6mA supply current each amplifier. Low noise. Good AC specs.

LT1498/LT1499: Dual or quad 10MHz, $6V/\mu s$, single 2.2V to $\pm 15V$ supplies, 1.7mA supply current per amplifier, input/output swings rail-to-rail. Excellent AC and DC specs.

LT1630: Dual or quad 30MHz, $10V/\mu$ s, single 2.7V to $\pm 15V$ supplies, 3.5mA supply current per amplifier, input/output swings rail-to-rail. Good AC and DC specs.

Internal Reference

The LTC1401 has an on-chip, temperature compensated, curvature corrected, bandgap reference, which is factory trimmed to 1.20V. It is internally connected to the DAC and

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is available at Pin 3 to provide up to 1mA current to an external load. For minimum code transition noise, the reference output should be decoupled with a capacitor to filter wideband noise from the reference (10uF tantalum in parallel with a 0.1uF ceramic is recommended). The V_{REF} pin can be driven with a DAC or other means to provide input span adjustment. The V_{REF} pin must be driven to at least 1.25V to prevent conflict with the internal reference. The reference should not be driven to more than 3V.

Figure 6 shows an LT1360 op amp driving the reference pin. Figure 7 shows a typical reference (LT1634-1.25) connected to the LTC1401. This will provide improved drift (equal to the maximum 25ppm/°C of the LT1634-1.25) and a 2.1338V full scale.

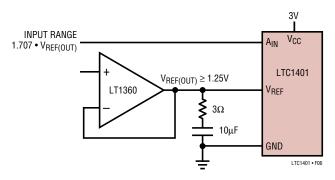


Figure 6. Driving the V_{REF} with the LT1360 Op Amp

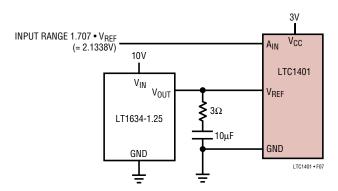


Figure 7. Supplying a 2.5V Reference Voltage to the LTC1401 with the LT1634-1.25

UNIPOLAR OPERATION AND ADJUSTMENT

Figure 8 shows the ideal input/output characteristics for the LTC1401. The code transitions occur midway between successive integer LSB values (i.e., 0.5LSB, 1.5LSB, 2.5LSB, ... FS – 1.5LSB). The output code is natural binary with 1LSB = 2.048/4096 = 0.5mV.

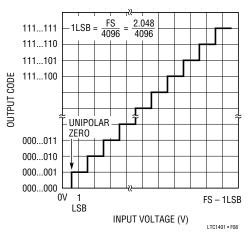


Figure 8. LTC1401 Unipolar Transfer Characteristics

Unipolar Offset and Full-Scale Error Adjustments

In applications where absolute accuracy is important, the offset and full-scale errors can be adjusted to zero. Offset error must be adjusted before full-scale error. Figure 9a shows the extra components required for full scale error adjustment. If both offset and full-scale adjustments are needed, the circuit in Figure 9b can be used. For zero offset error, apply 0.25mV (i.e., 0.5LSB) at the input and adjust the offset trim until the LTC1401 output code flickers between 0000 0000 0000 and 0000 0000 0001. For zero full-scale error, apply an analog input of 2.04725V (FS – 1.5LSB or last code transition) at the input and adjust R5 until the LTC1401 output code flickers between 1111 1111 1110 and 1111 1111.



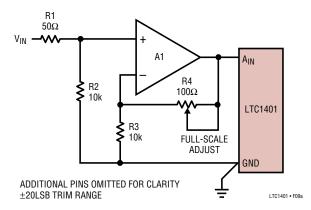


Figure 9a. LTC1401 Full-Scale Adjust Circuit

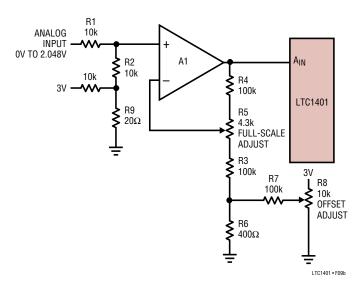


Figure 9b. LTC1401 Offset and Full-Scale Adjust Circuit

BOARD LAYOUT AND BYPASSING

Wire wrap boards are not recommended for high resolution or high speed A/D converters. To obtain the best performance from the LTC1401, a printed circuit board is required. Layout for the printed circuit board should ensure that digital and analog signal lines are separated as much as possible. In particular, care should be taken not to run any digital traces alongside an analog signal trace or underneath the ADC. The analog input should be screened by GND.

High quality tantalum and ceramic bypass capacitors should be used at the V_{CC} and V_{REF} pins as shown in the Typical Application on the first page of this datasheet. For

optimum performance, a 10μ F surface mount AVX capacitor in parallel with a 0.1μ F ceramic is recommended for the V_{CC} and V_{REF} pins. The capacitors must be located as close to the pins as possible. The traces connecting the pins and the bypass capacitors must be kept short and should be made as wide as possible.

Input signal leads to A_{IN} and signal return leads from GND (Pin 4) should be kept as short as possible to minimize noise coupling. In applications where this is not possible, a shielded cable between the analog input signal and the ADC is recommended. Also, any potential difference in grounds between the analog signal and the ADC appears as an error voltage in series with the analog input signal. Attention should be paid to reducing the ground circuit impedance as much as possible.

Figure 10 shows the recommended system ground connections. All analog circuitry grounds should be terminated at the LTC1401 GND pin. The ground return to the power supply from Pin 4 should be low impedance for noise free operation. Digital circuitry grounds must be connected to the digital supply common.

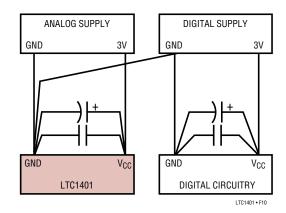


Figure 10. Power Supply Connection

Power-Down Mode

Upon power up, the LTC1401 is initialized to the active state and is ready for conversion. However, the chip can be easily placed into Nap or Sleep mode by exercising the right combination of CLK and CONV signals. In Nap mode, all power is off except the internal reference which remains active and provides 1.20V output voltage to the other



circuitry. In this mode, the ADC draws only 1.5mW of power instead of 15mW (for minimum power, the logic inputs must be within 500mV of the supply rails). The wake-up time from Nap mode to active mode is 350ns. In Sleep mode, power consumption is reduced to 19.5μ W by cutting off the supply to the comparator and reference. Figure 11 illustrates power-down methods for the LTC1401. The chip enters Nap mode by keeping the CLK signal low and pulsing the CONV signal twice. For Sleep mode operation, CONV signal should be pulsed four times while CLK is kept low. NAP and SLEEP modes are activated on the falling edge of the CONV pulse. By pulling SHDN low, the LTC1401 enters Shutdown mode and power consumption drops to 13.5μ W.

Once SHDN goes high, the LTC1401 returns to active mode or the LTC1401 returns to active mode by pulsing the CLK signal if the device has entered Nap/Sleep mode. During the transistion from Sleep mode to active mode, the V_{REF} voltage ramp-up time is a function of its loading conditions. With a 10µF bypass capacitor, the wake-up time from Sleep mode is typically 3ms. A REFRDY signal is activated once the reference has settled and is ready for

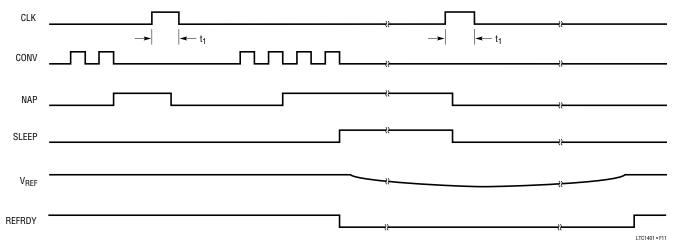
an A/D conversion. This REFRDY bit is sent to the D_{OUT} pin as the first bit followed by the 12-bit data word (refer to Figure 12).

DIGITAL INTERFACE

The digital interface requires only three digital lines. CLK and CONV are both inputs, and the D_{OUT} output provides the conversion result in serial form.

Figures 12 and 13 show the digital timing waveform of the LTC1401 during the Analog to Digital Conversion. The CONV rising edge starts the conversion. Once initiated, it can not be restarted until the conversion is completed. If the time from the CONV signal to the CLK rising edge is less than t_2 , the digital output will be delayed by one clock cycle.

The digital output data is updated on the rising edge of the CLK line. The digital output data consists of a REFRDY bit followed by the valid 12-bit data word. D_{OUT} data should be captured by the receiving system on the rising CLK edge. Data remains valid for a minimum time of t_{10} after the rising CLK edge to allow capture to occur.



NOTE: NAP AND SLEEP ARE INTERNAL SIGNALS. REFRDY APPEARS AS THE FIRST BIT IN THE DOUT WORD.

Figure 11. Nap Mode and Sleep Mode Waveforms



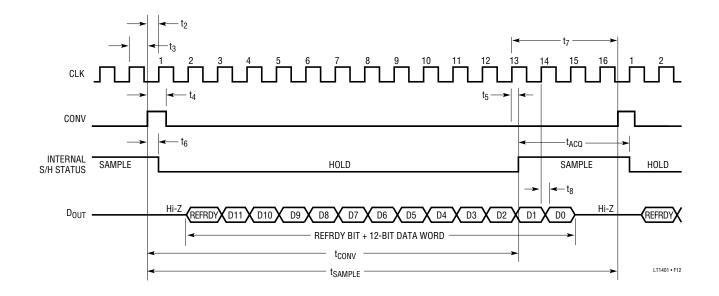
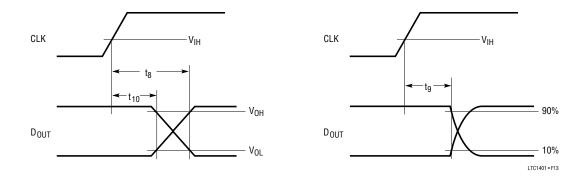
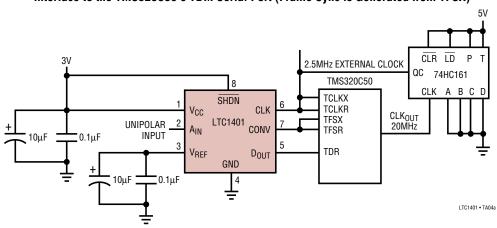


Figure 12. ADC Digital Timing Waveform



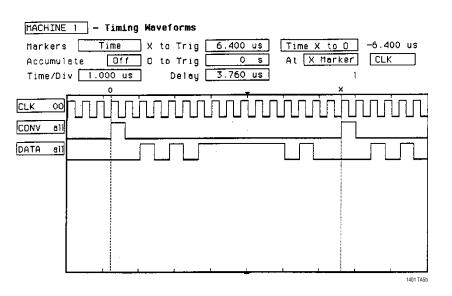




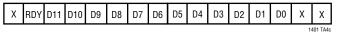


Interface to the TMS320C50's TDM Serial Port (Frame Sync is Generated from TFSX)

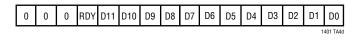
Logic Analyzer Waveforms Show 6.4 μ s Throughput Rate (Input Voltage = 0.765V, Output Code = 0101 1111 1010 = 1530₁₀)



Data from the LTC1401 Loaded into the TMS320C50's TRCV Register



Data Stored in the TMS320C50's Memory (in Right Justified Format)





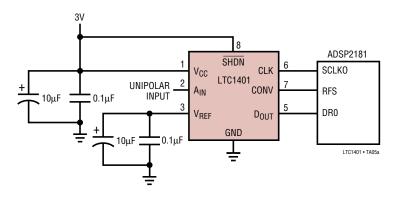
TMS320C50 Code for Circuit

THIS PROGRAM DEMONSTRATES THE LTC1401 INTERFACE TO THE TMS320C50. FRAME SYNC PULSE IS GENERATED FROM TFSX. DATA SHIFT CLOCK IS DERIVED FROM CLKOUT.

*Initializa				
mmr. Initiali:	egs ized data n	nomony	to zaro	; Defines global symbolic names
, minai	.ds	OFOOh		: Initialize data to zero
DATA0		0		; Begin sample data location
DATA1	.word	0		;.
DATA2	.word	0		; Location of data
DATA3	.word			
DATA4 DATA5		0 0		; . ; End sample data location
	the ISR v			
, 0010	.ps	080Ah	ı	; Serial ports interrupts
rint :	B	RECE	IVE	; 0A;
xint :	В		SMIT	; 0C;
trnt :	В	TREC		; 0E;
txnt :	B	TTRA	NX	; 10;
ps 04;;	the reset v	vector		
.ps or .entry				
START:				
TM6300	C50 Initial	ization		
	INTM	12011011		arily disable all interrupts
I DP	#0			a page pointer to zero
OPL	#0834h,	PMST	; Set up t	he PMST status and control register
LACC			.	
			; Set soft	ware wait state to 0
	/I PDWSR		,	
	re Serial Po			A Quedial David
SPLK	#0028h,	ISPC	,	<i>I</i> l Serial Port 0 Stand Alone mode
) Not loop back
			; FO = 0	
			,	1 Burst Mode
			; MCM =	0 CLKR is generated externally
				1 FSX as output pin
				al port into reset
כםו ע	#00E8h.	TODO		= RRST = 0) erial Port out of reset
SPLK	#UUEOII,	1010		= RRST = 1)
SPLK	#0FFFFh,	IFR		I the pending interrupts
	,		,	

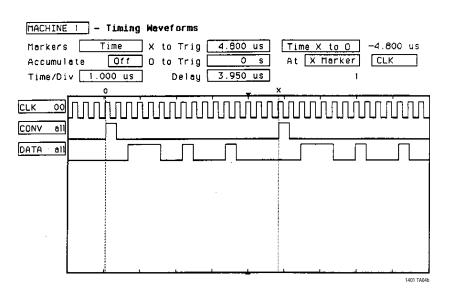
Start Seri	ial Communicatio	n
SACL	TDXR	; Generate frame sync pulse
SPLK	#040h, IMR	; Turn on TRNT receiver interrupt
CLRC		; Enable interrupt
CLRC		; For Unipolar input, set for right shift
OLITO	U.M.	; with no sign extension
MAR	*AD7	; Load the auxiliary register pointer with seven
	7.0.07	; Load the auxiliary register seven with #0F00h
LAN	AR7, #0F00h	; as the begin address for data storage
MALT.		
WAIT:	NOP	; Wait for a receive interrupt
	NOP	,
	NOP	, ,
SACL		; !! Regenerate the frame sync pulse
-	WAIT	• •
;	- end of main pro	gram ;
Receiver	Interrupt Service	Routine
TREC:		
LAMM	TRCV	; Load the data received from LTC1401
SFR		; Shift right two times
SFR		:
AND	#1FFFh, 0	ANDed with #1FFFh
	, .	; For converting the data to right
		; justified format
		·
SACL	*+ 0	, ; Write to data memory pointed by AR7 and
ONOL	1,0	; Increase the memory address by one
LACC	AB7	
	#0F05h,0	; Compare to end sample address #0F05h
		; If the end sample address has exceeded jump
DOND	END_INUV, GEQ	
		to END_TRCV
	#040h, IMR	; ; Else re-enable the TRNT receive interrupt
RFTF	#040H, HVIN	; Return to main program and enable interrupt
		om LTC1401, Program Jump to END_TRCV*
END_TRC		
SPLK	#002h, IMR	; Enable INT2 for program to halt
CLRC	INTM	
SUCCESS:		
В	SUCCESS	
Fill the ur	nused interrunt w	ith RETE, to avoid program get "lost"
TTRANX:	iuseu interrupt w	till HETE, to avoid program got lost
RETE		
RECEIVE:		
RETE		
	т.	
TRANSMI	1.	
RETE		
INT2:		
B halt		; Halts the running CPU





LTC1401 Interface to the ADSP2181's SPORTO (Frame Sync is Generated from RFS)

Logic Analyzer Waveforms Show 4.8µs Throughput Rate (Input Voltage = 1.604V, Output Code = 1100 1000 1000 = 3208₁₀)



Data from the LTC1401 (Normal Mode)

Х	RDY	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	Х	Х
														LTC14	01 • TA05

Data Stored in the ADSP2181's Memory (Normal Mode, SLEN = D)

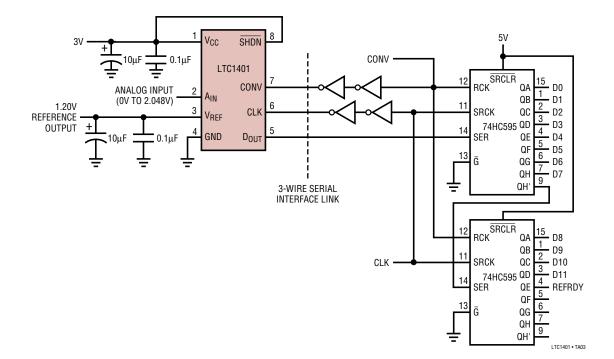
0 0 0 RDY D11 D10 D9 D8 D7 D6 D5 D4	D3	3 D2	2 D1	DO
-------------------------------------	----	------	------	----



ADSP2181 Code for Circuit

on 3: configure CLKDIV and RFS nfigure CLKDIV reg*/ = 4:	SDIV, setup interrupts*/
(0x3FF5) =ax0; /* set the seria SCLKDIV*/ /* the input cld /* CLKOUT fre /* SCLK= 1/2* /* for SCLKDIV nfigure RFSDIV*/ = 15; /* set the RFSI /*=> the fram /* if frame syn (0x3FF4) =ax0; tup interrupt*/ 0x0066; /* clear any ex I= 0; /* IRQXB = lev /* disable nest sk= 0x0020; /* bit 0 = timer /* bit 1 = SP0I /* bit 2 = SP0I /* bit 3 = BDM /* bit 4 = IRQE /* bit 5 = SP0I	RT1 or IRQ0B int = 0*/ RT1 or IRQ1B int = 0*/ IA int = 0*/ EB int = 0*/ RT0 receive int = 1*/
/* bit 7 = IRQ2 /*enable SPOI on 4: Configure System Control F nfigure system control reg*/ = dm(0x3FFF); /*read the s = 0xFF0; ax0 AND ay0; /*set wait s = 0x1000; ar OR ay0; /*bit 12 = 1 (0x3FFF) = ar; sync pulse regenerated automs = 5000; loop until ce; ; ; ;	RTO receive interrupt*/ Register and Start Communication*/ system control reg*/ state to zero*/ 1, enable SPORTO*/
me ntr ait op op op op op op op	me sync pulse regenerated autom ntr = 5000; aitloop until ce; op; op; op; op; op; op; pop; pop;



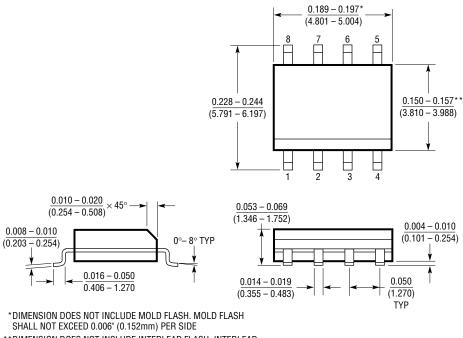


Quick Look Circuit for Converting Data to Parallel Format



PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.

S8 Package 8-Lead Plastic Small Outline (Narrow 0.150) (LTC DWG # 05-08-1610)

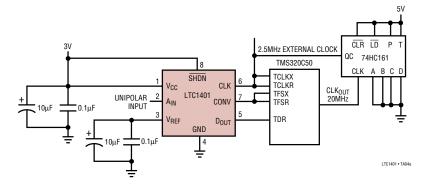


**DIMENSION DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" (0.254mm) PER SIDE

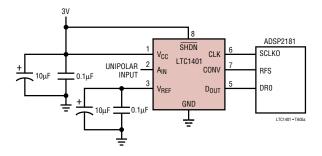
SO8 0996



Interface to the TMS320C50's TDM Serial Port (Frame Sync is Generated from TFSX)



LTC1401 Interface to the ADSP2181's SPORTO (Frame Sync is Generated from RFS)



RELATED PARTS

12-Bit Parallel Output ADCs

PART NUMBER	DESCRIPTION	COMMENTS	
LTC1273/LTC1275/LTC1276	Complete 5V Sampling 12-Bit ADCs with 70dB SINAD at Niquist	uist Lower Power and Cost Effective for $f_{SAMPLE} \le 300 ksps$	
LTC1274/LTC1277	Low Power 12-Bit ADCs with Nap and Sleep Mode Shutdown	Lowest Power (10mW) f _{SAMPLE} ≤ 100ksps	
LTC1278/LTC1279	High Speed Sampling 12-Bit ADCs with Shutdown	Cost Effective 12-Bit ADCs with Convert Start Input Best for 300ksps < $f_{SAMPLE} \leq 600ksps$	
LTC1282	Complete 3V 12-Bit ADCs with 12mW Power Dissipation	Fully Specified for 3V Powered Applications, $f_{SAMPLE} \le 140$ ksps	
LTC1409	Low Power 12-Bit, 800ksps Sampling ADC	Best Dynamic Performance f _{SAMPLE} ≤ 800ksps, 80mW Dissipation	
LTC1410	12-Bit, 1.25Msps Sampling ADC with Shutdown	Best Dynamic Performance, THD = –84dB and SINAD = 71dB at Nyquist	

12-Bit Serial Output ADCs

PART NUMBER	V _{CC}	SAMPLE RATE	POWER DISSIPATION	DESCRIPTION
LTC1285/LTC1288	3V	7.5/6.6ksps	0.48mW	3V, One or Two Input, Micropower, SO-8
LTC1286/LTC1298	5V	12.5/11.1ksps	1.25mV	One or Two Input, Micropower, SO-8
LTC1290	5/±5V	50ksps	30mW	8 Input, Full-Duplex Serial I/O
LTC1296	5/±5V	46.5ksps	30mW	8 Input, Half-Duplex Serial I/O, Power Shutdown Output
LTC1400	5/±5V	400ksps	75mW	Complete 12-Bit, 400ksps, SO-8 ADC with Shutdown
LTC1404	5/±5V	600ksps	75mW	Complete 12-Bit, 600ksps, SO-8 ADC with Shutdown

